

### General Description

The Sanrise SRC65R600E is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC65R600E break down voltage is 650V and it has a high rugged avalanche characteristics. The SRC65R600E is available in TO-252 and TO-220F packages.

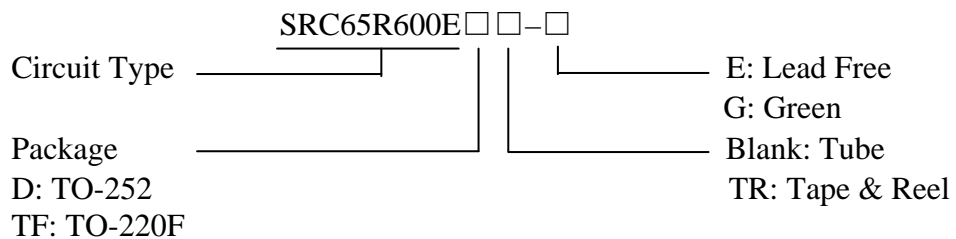
### Features

- Ultra Low  $R_{DS(ON)} = 600m\Omega @ V_{GS} = 10V$ .
- Ultra Low Gate Charge,  $Q_g = 18.4nC$  typ.
- Fast switching capability
- Robust design with better EAS performance
- EMI Improved Design (*SnowMOS™ Gen.2*)

### Application

- TV Power
- High Performance Charger / Adapter
- LED Lighting Power

### Ordering Information



### Symbol

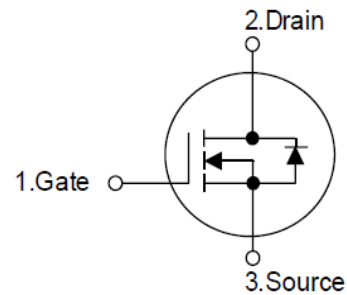


Figure 1 Symbol of SRC65R600E

### Package Type

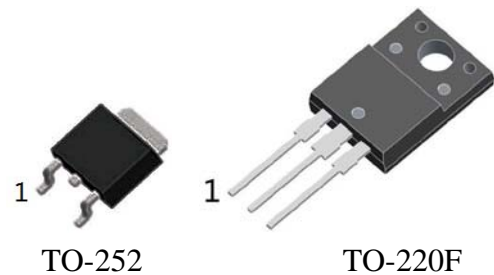


Figure 2 Package Types of SRC65R600E

| Package | Part Number     |                 | Marking ID     |                | Packing Type |
|---------|-----------------|-----------------|----------------|----------------|--------------|
|         | Lead Free       | Green           | Lead Free      | Green          |              |
| TO-252  | SRC65R600EDTR-E | SRC65R600EDTR-G | SRC65R600EDE   | SRC65R600EDG   | Tape & Reel  |
| TO-220F | SRC65R600ETF-E  | SRC65R600ETF-G  | SRC65R600ETF-E | SRC65R600ETF-G | Tube         |

**Absolute Maximum Ratings**

| Parameter                               |                                   | Symbol        | Rating     | Unit |
|---|-----------------------------------|---------------|------------|------|
| Drain-Source Voltage                    |                                   | $V_{DSS}$     | 680        | V    |
| Gate-Source Voltage                     |                                   | $V_{GSS}$     | ±30        | V    |
| Continuous Drain Current                | $T_C=25^{\circ}\text{C}$ (Note 2) | $I_D$         | 8.4        | A    |
|   | $T_C=125^{\circ}\text{C}$         |               | 3.3        |      |
| Pulsed Drain Current (Note 3)           |                                   | $I_{DM}$      | 24.0       | A    |
| Avalanche Energy, Single Pulse (Note 4) |                                   | $E_{AS}$      | 105        | mJ   |
| Avalanche Energy, Repetitive (Note 3)   |                                   | $E_{AR}$      | 0.15       | mJ   |
| Avalanche Current, Repetitive (Note 3)  |                                   | $I_{AR}$      | 1.3        | A    |
| Continuous Diode Forward Current        |                                   | $I_S$         | 7.3        | A    |
| Diode Pulse Current                     |                                   | $I_{S,PULSE}$ | 24.0       | A    |
| Operating Junction Temperature          |                                   | $T_J$         | 150        | °C   |
| Storage Temperature                     |                                   | $T_{STG}$     | -55 to 150 | °C   |
| Lead Temperature (Soldering, 10 sec)    |                                   | $T_{LEAD}$    | 300        | °C   |

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Limited by  $T_{J,MAX}$ , Maximum duty cycle  $D=0.75$
3. Repetitive Rating: Pulse width limited by maximum junction temperature
4.  $I_{AS} = 1.3\text{A}$ ,  $V_{DD} = 60\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^{\circ}\text{C}$

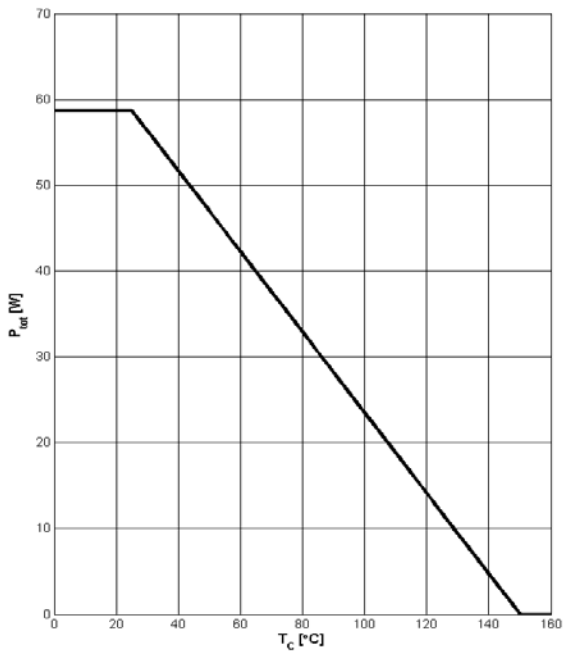
**Electrical Characteristics**
 $T_J = 25^\circ\text{C}$ , unless otherwise specified.

| Parameter   | Symbol        | Test Conditions                                   | Min | Typ  | Max  | Unit      |
|---|---------------|---|-----|------|------|-----------|
| <b>Statistic Characteristics</b>                              |               |   |     |      |      |           |
| Drain-Source Breakdown Voltage                                | $BV_{DSS}$    | $V_{GS}=0V, I_D=250\mu A$                         | 650 |      |      | V         |
| Zero Gate Voltage Drain Current                               | $I_{DSS}$     | $V_{DS}=650V, V_{GS}=0V$                          |     |      | 1    | $\mu A$   |
| Gate-Body Leakage Current                                     | Forward       | $I_{GSSF}, V_{GS}=30V, V_{DS}=0V$                 |     |      | 100  | nA        |
|   | Reverse       | $I_{GSSR}, V_{GS}=-30V, V_{DS}=0V$                |     |      | -100 |           |
| Gate Threshold Voltage  | $V_{GS(TH)}$  | $V_{DS}=V_{GS}, I_D=250\mu A$                     | 2.7 | 3.6  | 4.5  | V         |
| Static Drain-Source On-Resistance                             | $R_{DS(ON)}$  | $V_{GS}=10V, I_D=4.0A$                            |     | 460  | 600  | $m\Omega$ |
| Gate Resistance   | $R_G$         | $f=1MHz, \text{Open Drain}$                       |     | 8.9  |      | $\Omega$  |
| <b>Dynamic Characteristics</b>                                |               |   |     |      |      |           |
| Input Capacitance   | $C_{ISS}$     | $V_{DS}=50V, V_{GS}=0V, f=1MHz$                   |     | 356  |      | pF        |
| Output Capacitance  | $C_{OSS}$     |   |     | 31.8 |      |           |
| Reverse Transfer Capacitance                                  | $C_{RSS}$     |   |     | 18.7 |      |           |
| Effective output capacitance, energy related <sup>NOTE5</sup> | $C_{O(er)}$   | $V_{GS}=0V, V_{DS}=0\dots 480V$                   |     | 16   |      | pF        |
| Effective output capacitance, time related <sup>NOTE6</sup>   | $C_{O(tr)}$   |   |     | 72   |      |           |
| Turn-on Delay Time  | $t_{d(on)}$   | $V_{DD}=400V, I_D=4.0A, R_G=10\Omega, V_{GS}=10V$ |     | 10   |      | ns        |
| Rise Time   | $t_r$         |   |     | 12   |      |           |
| Turn-off Delay Time   | $t_{d(off)}$  |   |     | 36   |      |           |
| Fall Time   | $t_f$         |   |     | 14   |      |           |
| <b>Gate Charge Characteristics</b>                            |               |   |     |      |      |           |
| Gate to Source Charge   | $Q_{gs}$      | $V_{DD}=480V, I_D=4.0A, V_{GS}=0 \text{ to } 10V$ |     | 4.2  |      | nC        |
| Gate to Drain Charge  | $Q_{gd}$      |   |     | 9.1  |      |           |
| Gate Charge Total   | $Q_g$         |   |     | 18.4 |      |           |
| Gate Plateau Voltage  | $V_{plateau}$ |   |     | 5.9  |      | V         |
| <b>Reverse Diode Characteristics</b>                          |               |   |     |      |      |           |
| Drain-Source Diode Forward Voltage                            | $V_{SD}$      | $V_{GS}=0V, I_{SD}=4.0A$                          |     | 0.84 | 1.1  | V         |
| Reverse Recovery Time   | $t_{rr}$      | $V_R=400V, I_F=4.0A, dI_F/dt=100A/\mu s$          |     | 206  |      | ns        |
| Reverse Recovery Charge                                       | $Q_{rr}$      |   |     | 1.63 |      | $\mu C$   |
| Peak Reverse Recovery Current                                 | $I_{rrm}$     |   |     | 15.8 |      | A         |

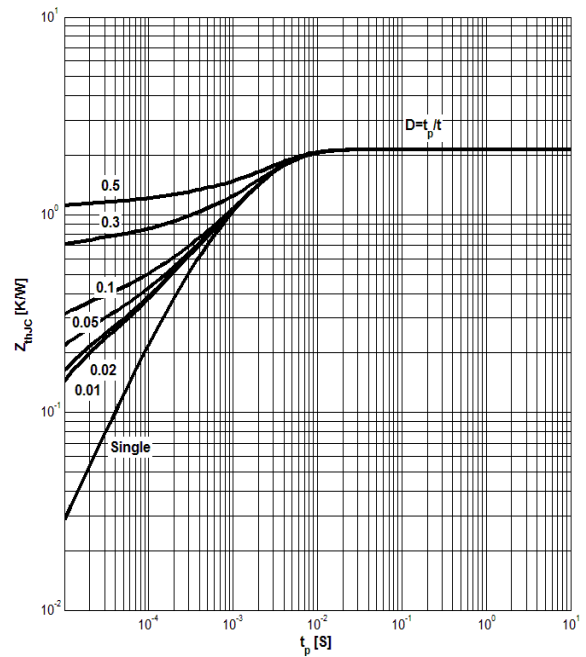
Note:

 5.  $C_{O(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 480V

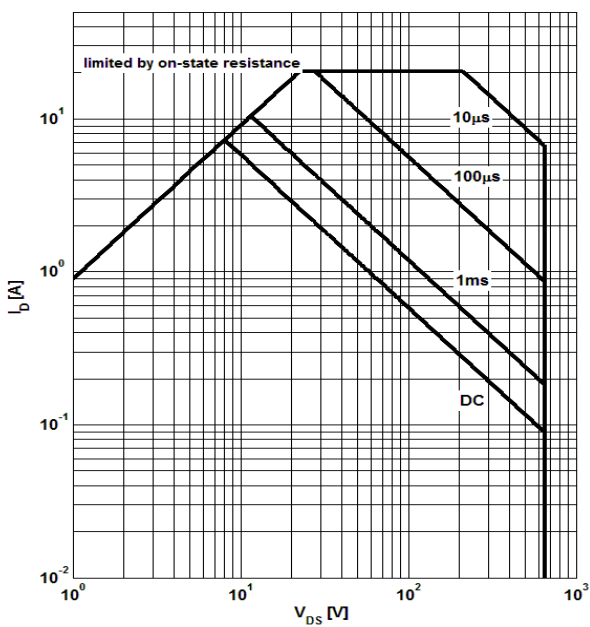
 6.  $C_{O(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 480 V

**Typical Performance Characteristics**
**Figure 1: Power Dissipation**


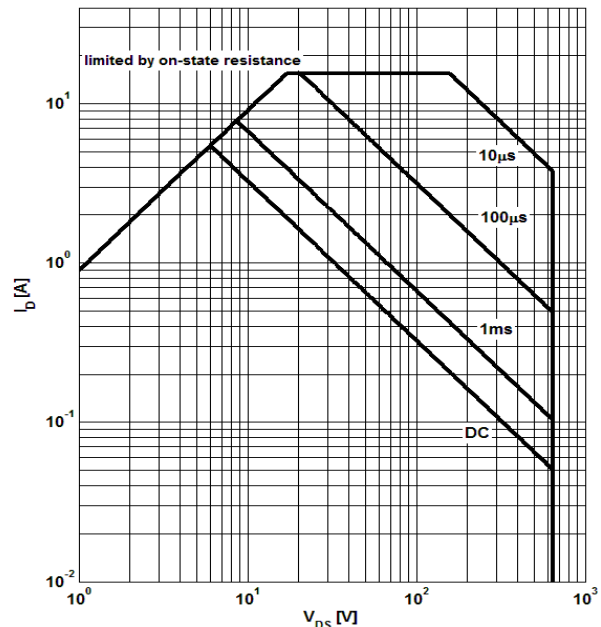
$$P_{tot} = f(T_c)$$

**Figure 2: Max. Transient Thermal Impedance**


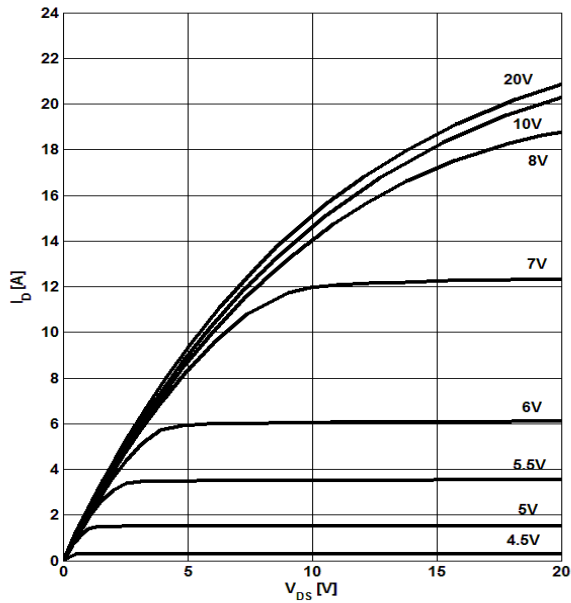
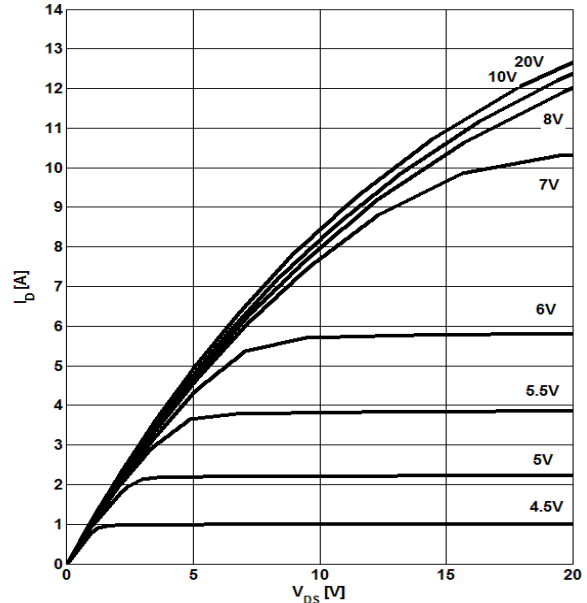
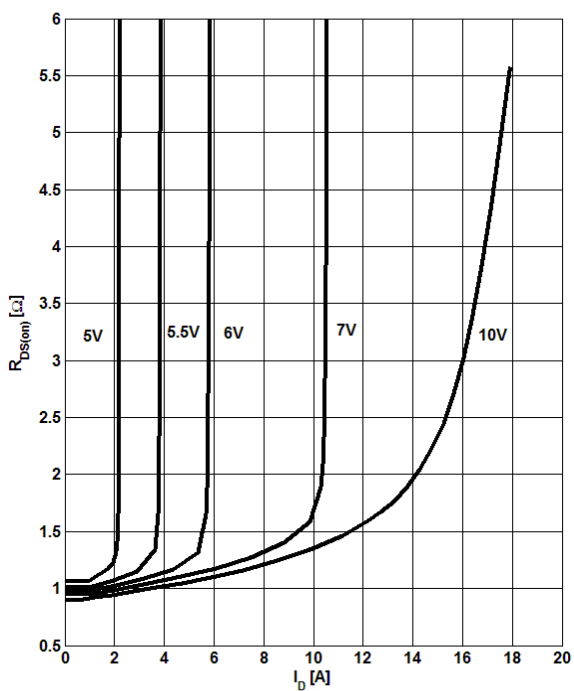
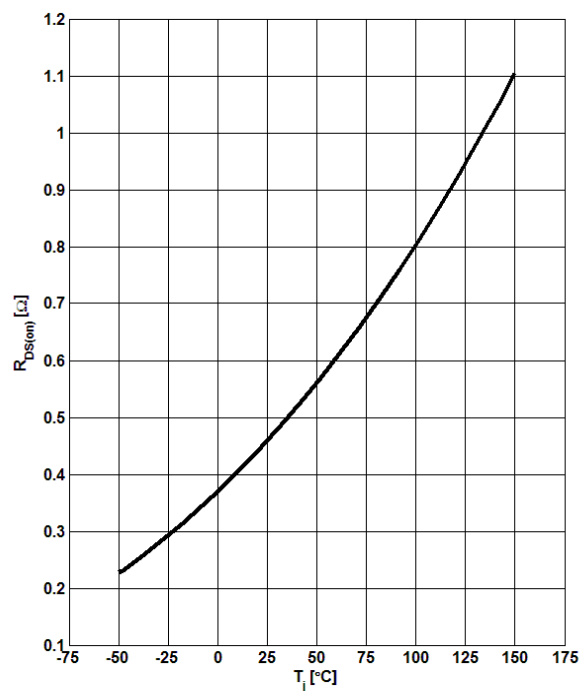
$$Z_{th(jc)} = f(t_p); \text{ parameter: } D = t_p/T$$

**Figure 3: Safe Operating Area**


$$I_D = f(V_{DS}); T_c = 25^\circ\text{C}; V_{GS} > 7\text{V}; \text{ parameter } t_p$$

**Figure 4: Safe Operating Area**


$$I_D = f(V_{DS}); T_c = 80^\circ\text{C}; V_{GS} > 7\text{V}; \text{ parameter } t_p$$

**Figure 5: Typ. Output Characteristics**

 $I_D = f(V_{DS}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GS}$ 
**Figure 6: Typ. Output Characteristics**

 $I_D = f(V_{DS}); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$ 
**Figure 7: Typ. Drain-Source On-State Resistance**

 $R_{DS(ON)} = f(I_D); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$ 
**Figure 8: Typ. Drain-Source On-State Resistance**

 $R_{DS(ON)} = f(T_j); I_D = 4.0\text{A}; V_{GS} = 10\text{V}$

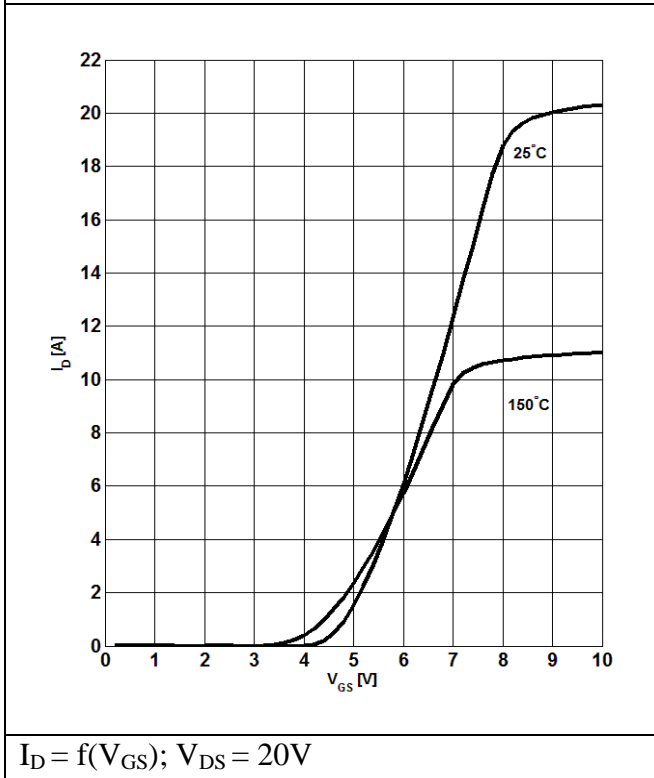
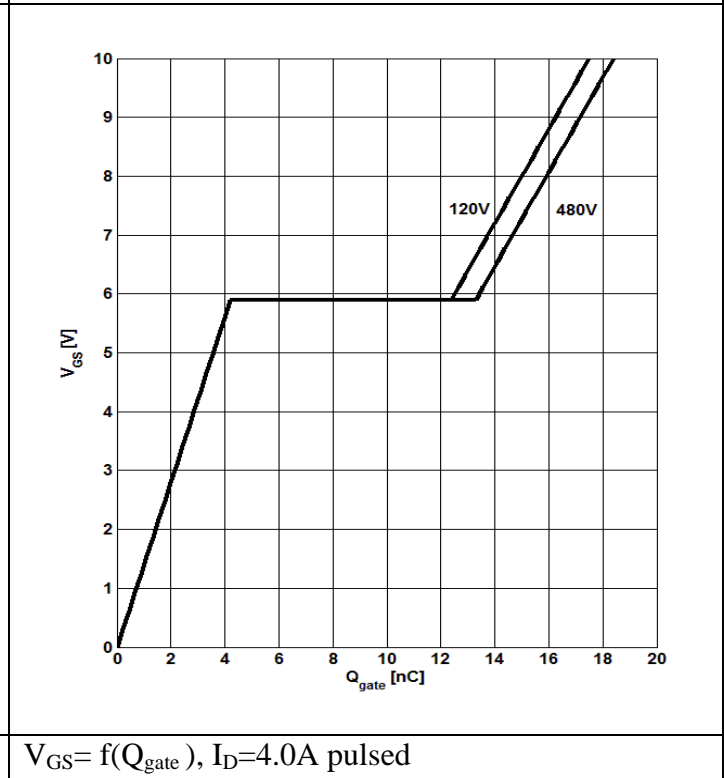
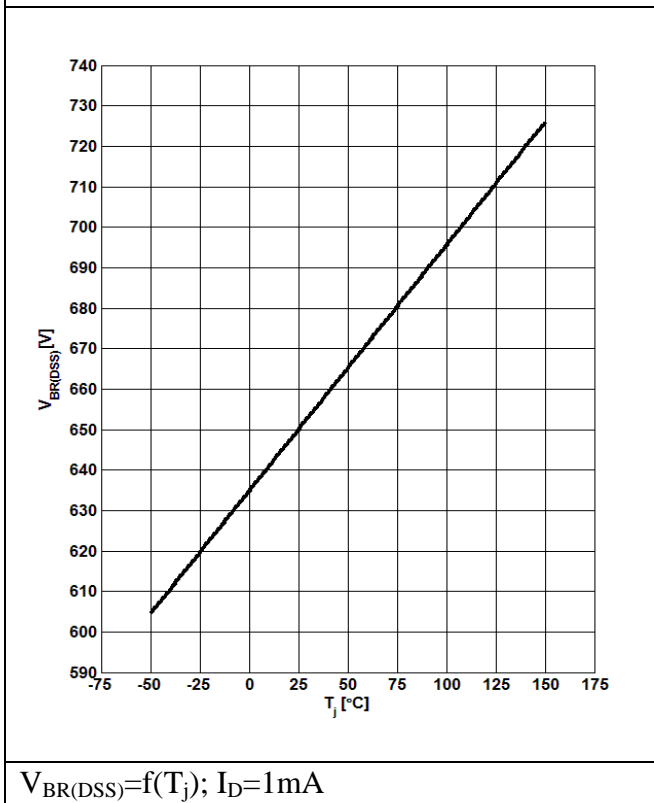
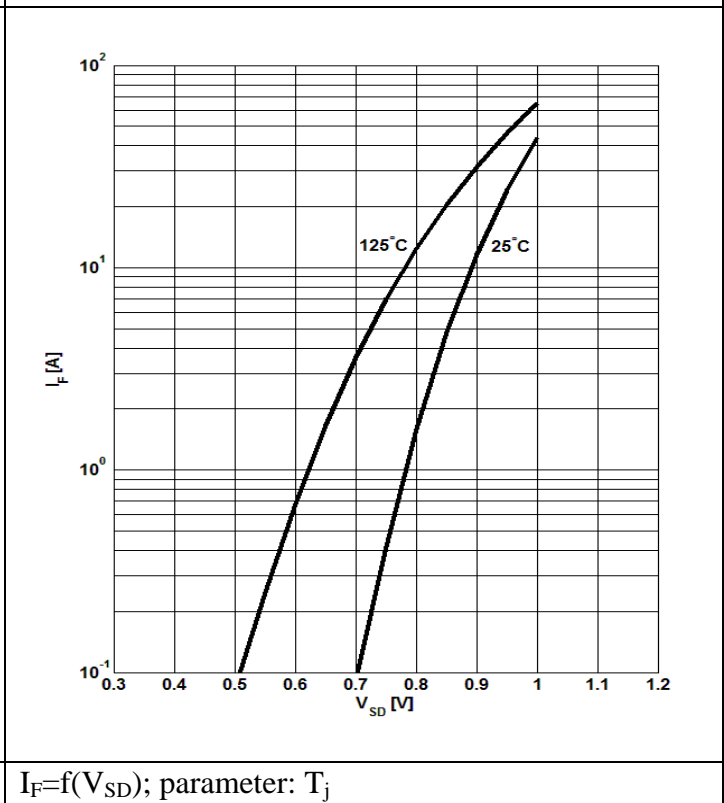
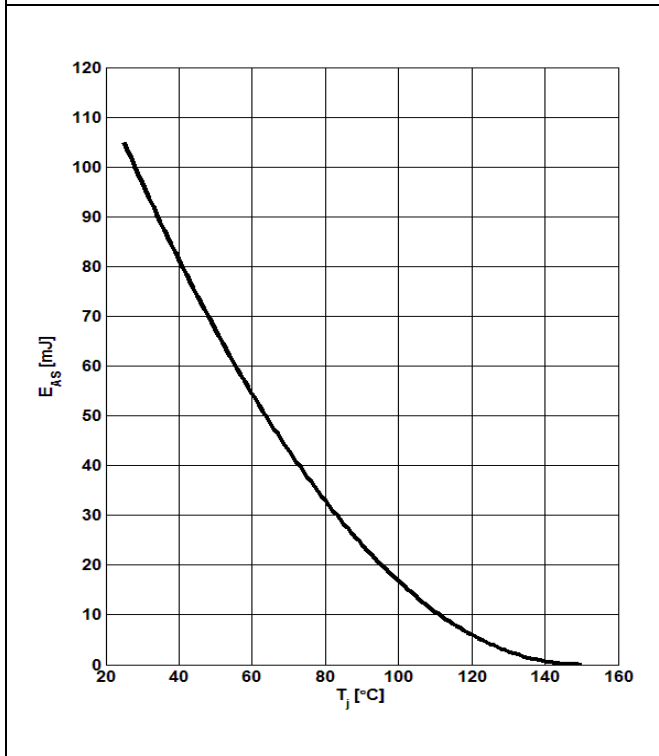
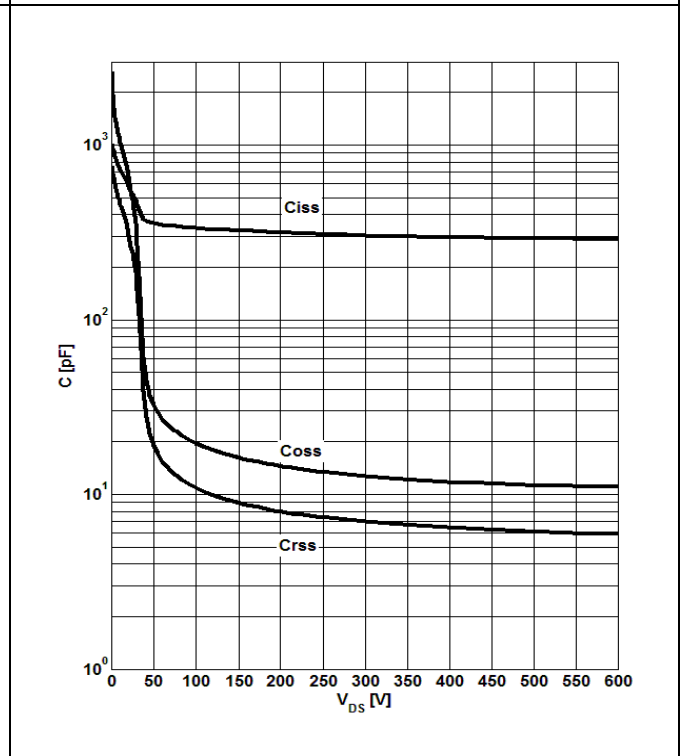
**Figure 9: Typ. Transfer Characteristics**

**Figure 10: Typ. Gate Charge**

**Figure 11: Drain-Source Breakdown Voltage**

**Figure 12: Forward Characteristics of Reverse Diode**


Figure 13: Avalanche Energy



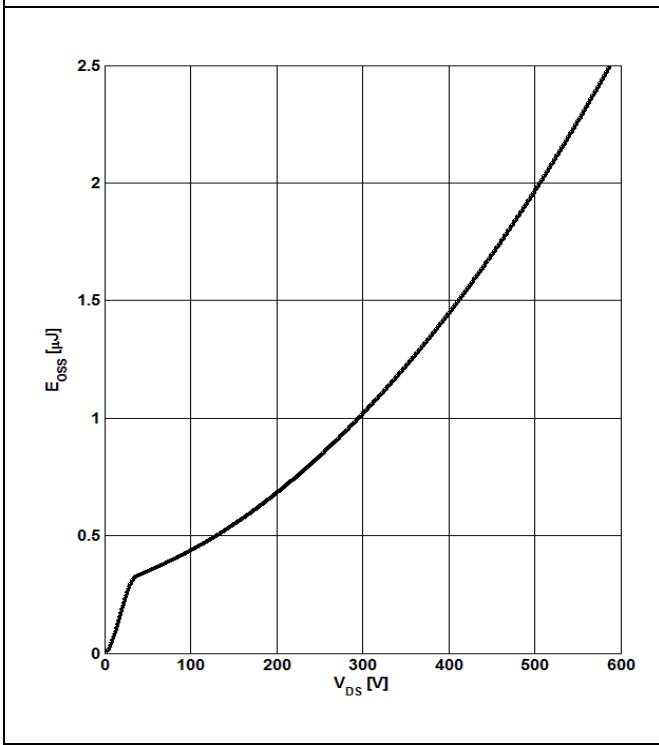
$E_{AS}=f(T_j); I_D=1.3A; V_{DD}=60V$

Figure 14: Typ. Capacitances

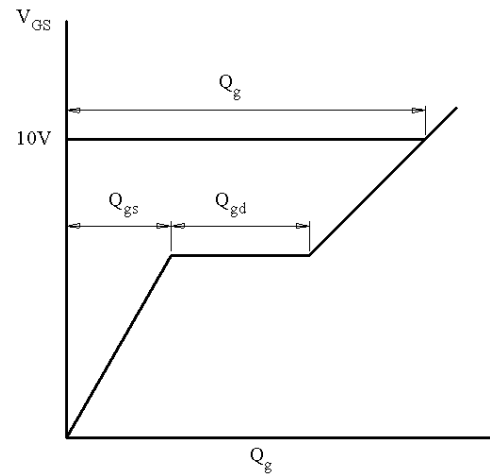
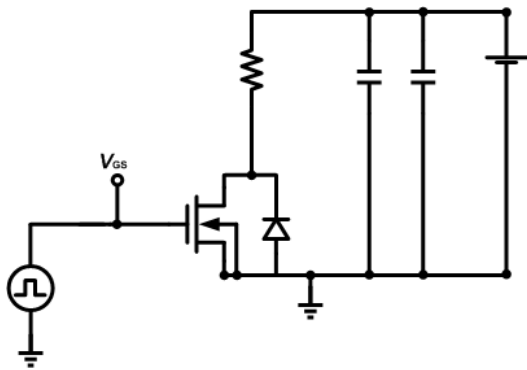
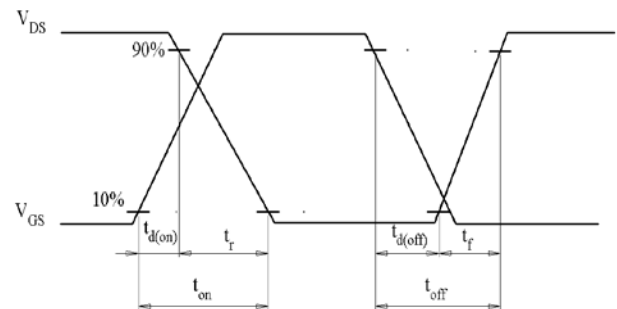
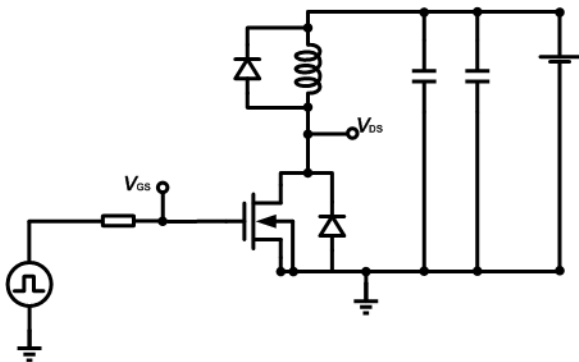
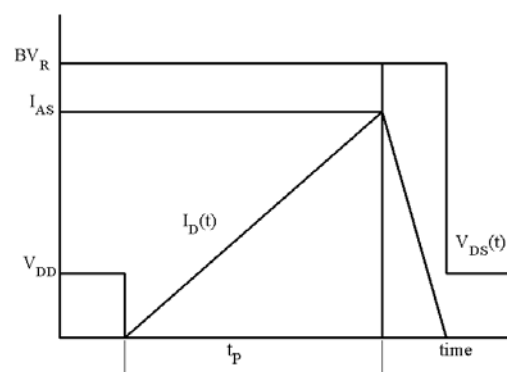
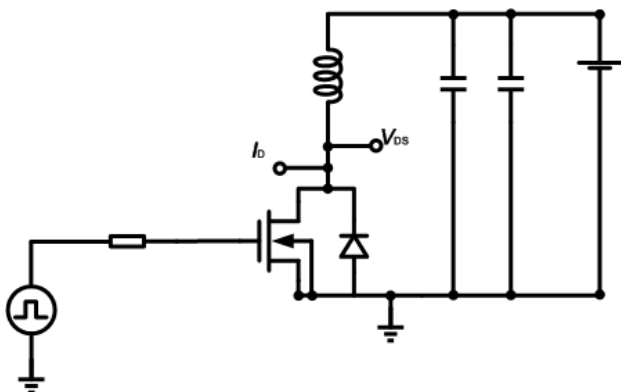


$C=f(V_{DS}); V_{GS}=0; f=1MHz$

Figure 15: C<sub>oss</sub> Stored Energy

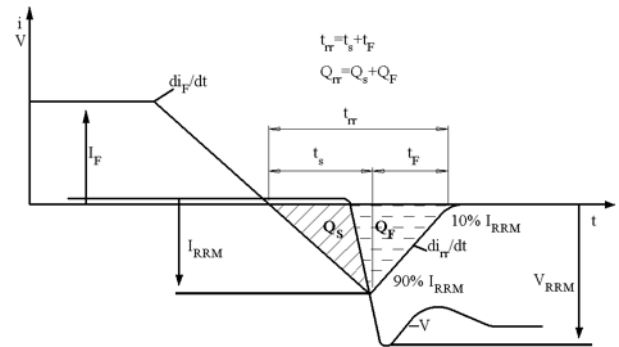
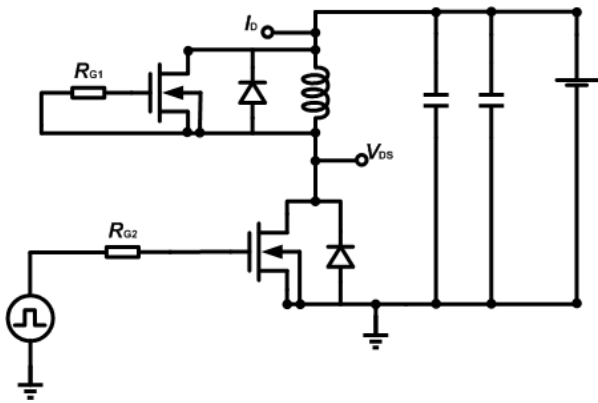


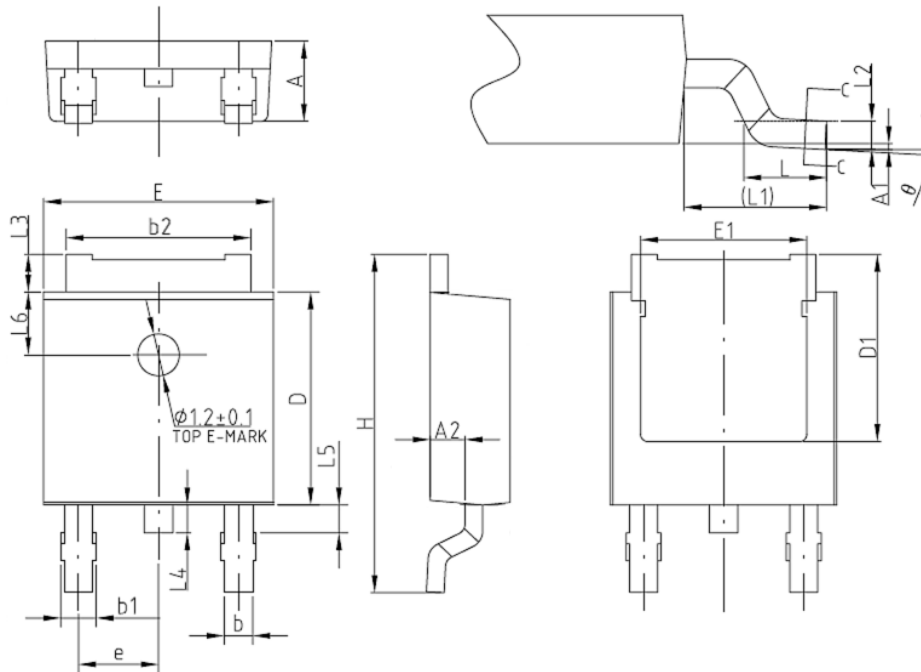
$E_{OSS}=f(V_{DS})$

**Test Circuits**
**1. Gate Charge Test Circuit & Waveform**

**2. Switch Time Test Circuit**

**3. Unclaimed Inductive Switching Test Circuit & Waveforms**




**4. Test Circuit and Waveform for Diode Characteristics**

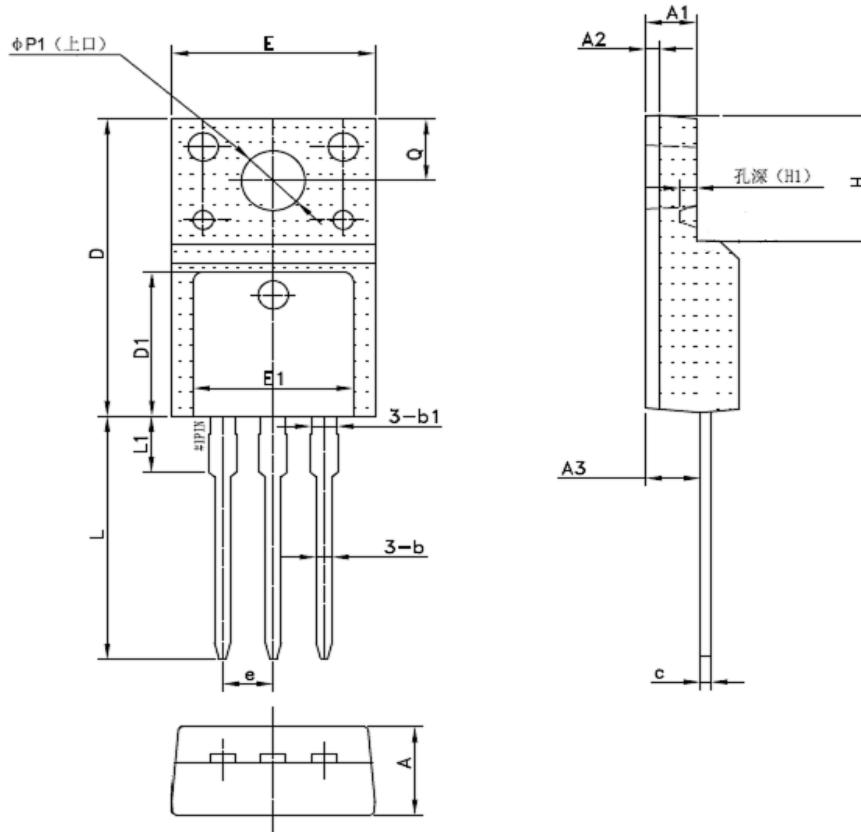


**Mechanical Dimensions**
**TO-252**
**Unit: mm**


| Symbol | Dimensions(mm) |       |       |
|--------|----------------|-------|-------|
|        | Min.           | Typ.  | Max.  |
| A      | 2.20           | 2.30  | 2.40  |
| A1     | 0              | -     | 0.10  |
| A2     | 0.90           | 1.00  | 1.17  |
| b      | 0.70           | 0.76  | 0.90  |
| b1     | 0.77           | -     | 1.10  |
| b2     | 5.13           | 5.33  | 5.46  |
| c      | 0.45           | -     | 0.60  |
| D      | 5.95           | 6.10  | 6.25  |
| D1     | -              | 5.30  | -     |
| E      | 6.45           | 6.60  | 6.75  |
| E1     | -              | 4.80  | -     |
| e      | 2.286(BSC)     |       |       |
| H      | 9.70           | 10.10 | 10.40 |
| L      | 1.25           | 1.50  | 1.75  |
| L1     | -              | 2.90  | -     |
| L2     | -              | 0.51  | -     |
| L3     | 0.90           | -     | 1.25  |
| L4     | -              | 0.80  | -     |
| L5     | -              | 1.00  | -     |
| L6     | -              | 1.80  | -     |
| θ      | 0°             | -     | 8°    |

**Mechanical Dimensions (Continued)**
**TO-220F**

Unit: mm



| Symbol | Dimensions(mm) |        |       |
|--------|----------------|--------|-------|
|        | Min.           | Typ.   | Max.  |
| A      | 4.30           | 4.70   | 4.90  |
| A1     | 2.34           | 2.54   | 2.90  |
| A2     | -              | 0.70   | -     |
| A3     | 2.56           | 2.76   | 2.96  |
| b      | 0.55           | -      | 0.95  |
| b1     | -              | 1.28   | -     |
| c      | 0.42           | 0.50   | 0.70  |
| D      | 14.70          | -      | 16.07 |
| D1     | -              | 7.70   | -     |
| E      | 9.96           | 10.16  | 10.36 |
| E1     | -              | 8.00   | -     |
| e      | 2.54(BSC)      |        |       |
| H      | -              | 6.70   | -     |
| (H1)   | -              | (0.81) | -     |
| L      | 12.48          | 12.98  | 13.50 |
| L1     | -              | 2.93   | -     |
| ΦP1    | -              | 3.18   | -     |
| Q      | 2.90           | 3.30   | 3.50  |



Sanrise Technology Limited Company

<http://www.sanrise-tech.com>

#### **IMPORTANT NOTICE**

Sanrise Technology Limited Company reserves the right to make changes without further notice to any products or specifications herein. Sanrise Technology Limited Company does not assume any responsibility for use of any its products for any particular purpose, nor does Sanrise Technology Limited Company assume any liability arising out of the application or use of any its products or circuits. Sanrise Technology Limited Company does not convey any license under its patent rights or other rights nor the rights of others.

---

#### **Main Site:**

##### **- Headquarter**

Sanrise Technology Limited Company  
Rm.601~603, Building B, SDG Information Port, No.2,  
Kefeng Road, Science & Technology Park, Nanshan District,  
ShenZhen, China  
Tel: +86-755-22953335  
Fax: +86-755-22916878

##### **- Shanghai Office**

Sanrise Technology Limited Company  
No. 1159, Cailun Road, Zhangjiang HiTech Park,  
Pudong District, Shanghai, China  
Tel: +86-21-51355061